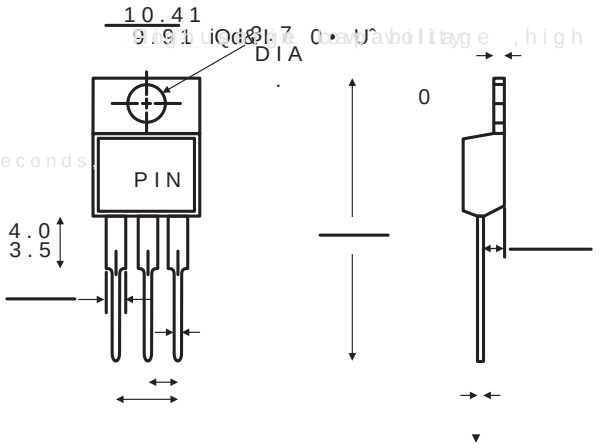
72 $% 3/$67,&&25(&7,),(56

High temperature soldering guaranteed:260 C/10 seconds,
0.25"(6.35mm)from case
Component in accordance to RoHS 2002/95/EC and
WEEE 2002/96/EC

0(&+$1,&$/ '7

2.Reverse recovery test conditions



0$;,080 5$7,1*6 $1' &+$5$&7(5,67,&6

&$SPELHQW WHPSHUDWXUH XQOHVV RWKHUZLVH QRWHG

	Symbols	MURF 1620CT	MURF 1640CT	MURF 1660CT	Units
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	Volts
Maximum RMS voltage	V_{RMS}	140	280	420	Volts
Maximum DC blocking voltage	V_{DC}	200	400	600	Volts
Maximum average forward rectified current(see Fig.1) — Per leg	$I_{(AV)}$	8.0			Amps
Maximum average forward rectified current(see Fig.1) — Total device	$I_{(AV)}$	8.0			Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	100			Amps
Maximum instantaneous forward voltage at 10.0 A(Note 1)	V_F	0.975	1.3	1.7	Volts
Maximum instantaneous reverse current at rated DC blocking voltage(Note 1) — T_A=25 °C	I_R	5	10		uA
Maximum instantaneous reverse current at rated DC blocking voltage(Note 1) — T_A=125 °C	I_R	500			uA
Maximum Reverse Recovery Time (Note 2)	T_{rr}	35			ns
Typical thermal resistance (Note 3)	$R_{\theta JC}$	3.0			C/W
Operating junction temperature range	T_J	-65 to+175			C
Storage temperature range	T_{STG}	-65 to+175			°C

I_F=0.5A, I_R=1.0A, Irr=0.25A

3. Thermal resistance from junction to case

6

CHARACTE

2 F W